

CH03-BF - SIM CARD HOLDER 6 OR 8 PINS WITHOUT SWITCH

FEATURES

1. GENERAL CHARACTERISTICS
 DIMENSIONS: 29.60L x 17.20W x 3.00H mm
 WEIGHT: APPROX. 1.34g
 CONTACT PRINCIPLE: FRICTION TECHNOLOGY
 OPERATING POSITION: SHAFT UP / DOWN / HORIZONTAL
 MOUNTING SYSTEM: SMT TYPE
 DURABILITY: 10,000 CYCLES MIN.

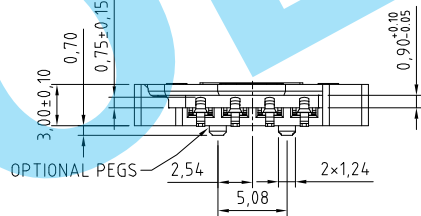
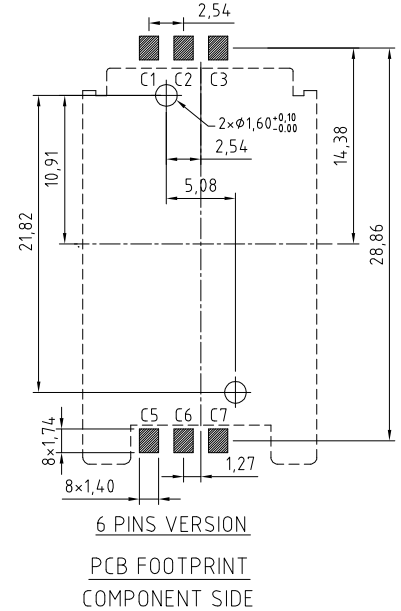
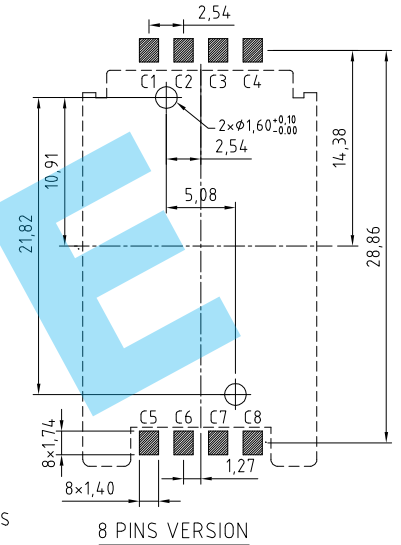
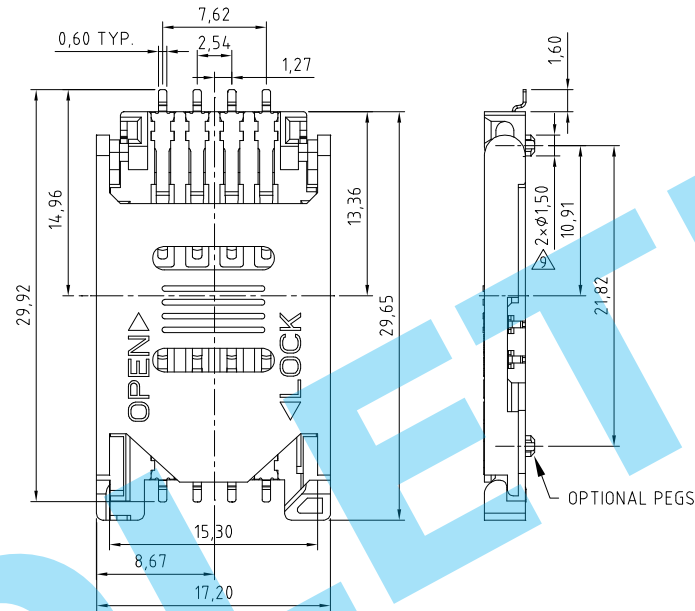
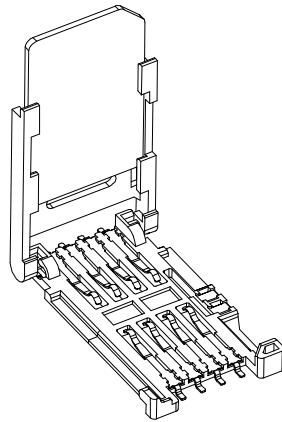
2. MECHANICAL CHARACTERISTICS
 INSULATION MATERIAL: THERMOPLASTIC, UL 94 V-0
 CONTACT PLATING: GOLD FLASH ON CONTACT AREA, TIN ON TAIL

3. ELECTRICAL CHARACTERISTICS
 NUMBER OF CONTACTS (OPTIONAL): 6, 8 PINS
 CONTACT RESISTANCE: 50M OHMS TYP. 100M OHMS MAX.
 INSULATION RESISTANCE: > 1000M OHMS / 500V DC

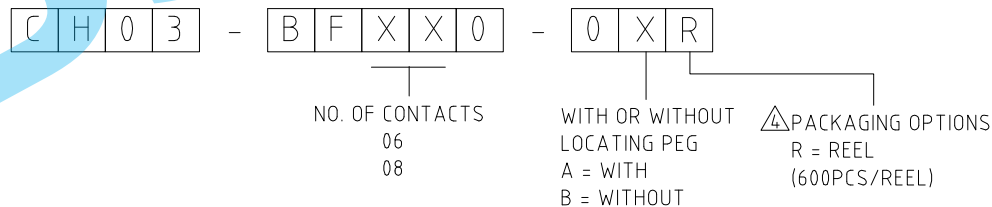
4. SOLDERABILITY
 WAVE: NOT APPLICABLE
 IR REFLOW: 260°C, 10 SEC. MAX. Δ
 MANUAL SOLDERING: 360°C, 3 SEC. MAX.

5. ENVIRONMENTAL CHARACTERISTICS
 OPERATING TEMPERATURE: -40°C ~ +85°C
 OPERATING HUMIDITY: 10% ~ 95% RH
 STORAGE TEMPERATURE: -40°C ~ +85°C
 STORAGE HUMIDITY: 10% ~ 95% RH
 THERMAL SHOCK -40°C ~ +85°C, 5 CYCLES
 DAMP HEAT: 40°C, 90% RH, 500 HR
 SALT MIST: 35°C, 5%, NaCl, 48 HR

NOTES:
 1. ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11 SPECIFICATION REQUIREMENT. Δ



HOW TO ORDER



REV.	DATE & DRN
10	14/09/04 - NYW - RELEASE
11	17/10/06 - CIC
Δ	AMND MAX TEMP
12	29/05/07 - NYW
Δ	ADD NOTES 1
13	21/06/07 - NYW
Δ	ADD CONTACT PLATING
14	28/09/07 - NYW
Δ	REMOVE PEEK OPTION TRAY
15	21/11/07 - NYW
Δ	ADD SEPARATE PGB LAYOUT
16	28/04/09 - PN
	PACKAGING DRAWING ADDED
17	04/01/10 - NYW
	DRAWING MODIFICATION
18	22/02/11 - NYW
	INSULATOR BASE CHANGE
	1.5 DRAWING CHANGE
Δ	DRAWING AMENDMENT

Scale:	2.5:1	THIRD ANGLE	Unstated Tolerances: 0 Dec Places 1 Dec Places 2 Dec Places 3 Dec Places	Material	SEE NOTE
Drawn:	NYW				
App'd:	XXXX	Title	SIM CARD ACCEPTOR	NOT TO SCALE	
Date:	28 JUN '12	Revision:	1.9	Unit:	mm

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Type:	CH03-BF
Drawing Number:	CH03-BF
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